

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)	Q _g (Typ)		
- 60	0.063 at V _{GS} = - 10 V	- 25	25		
- 60	0.075 at V _{GS} = - 4.5 V	- 20	25		

FEATURES

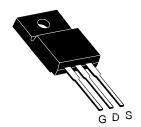
- TrenchFET® Power MOSFET
- 100 % UIS Tested

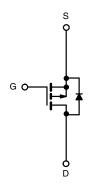


APPLICATIONS

Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 2$	25 °C, unless othe	rwise noted		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	I-	- 25	
Continuous Diain Current (1) = 175 C)	T _C = 100 °C	I _D	- 18	
Pulsed Drain Current		I _{DM}	- 60	A
Continuing Source Current (Diode Conduction)		I _S	- 16	
Avalanche Current		I _{AS}	- 16	
Single Pulse Avalanche Energy L = 0.1 r		E _{AS}	7.2	mJ
Maximum Daylar Dissination	T _C = 25 °C	В	60 ^a	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	5 ^b	W
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
hunding to Ambient	t ≤ 10 sec	R _{thJA}	20 25	25			
Junction-to-Ambient ^D	Steady State	' 'thJA	62	75	°C/W		
Junction-to-Case		R _{thJC}	5	6			

Notes:

- a. See SOA curve for voltage derating.
- b. Surface Mounted on 1" x 1" FR-4 boad.

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Parameter	Symbol	Test Conditions	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0	- 2.0	- 3.0	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V _{DS} = - 60 V, V _{GS} = 0 V			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 175 °C			- 150	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 10			Α
		V _{GS} = - 10 V, I _D = - 5 A		0.063		
	_	V _{GS} = - 10 V, I _D = - 5 A, T _J = 125 °C		0.140		0
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = - 10 V, I _D = - 5 A, T _J = 175 °C		0.260		77
		V _{GS} = - 4.5 V, I _D = - 2 A		0.075		V nA μA A Ω S pF nC
Forward Transconductance ^b	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A		8		S
Dynamic		<u> </u>		!	···········	
Input Capacitance	C _{iss}			850		pF
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120		
Reverse Transfer Capacitance	C _{rss}			90		
Total Gate Charge	Qg			13		
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8.4 \text{ A}$		2.3		nC
Gate-Drain Charge	Q_{gd}]		3.2		
Gate Resistance	R_g	f = 1 MHz	8.0			Ω
Turn-On Delay Time ^c	t _{d(on)}			5	10	
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V, R}_{L} = 3.57 \Omega$		14	25	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 8.4 A, V_{GEN} = - 10 V, R_G = 2.5 Ω		15	25	
Fall Time ^c	t _f	1		7	12	
Source-Drain Diode Ratings and Cha	racteristics	(T _C = 25 °C) ^b				
Pulsed Current	I _{SM}			- 20		Α
Forward Voltage ^b	V _{SD}	I _F = - 2 A, V _{GS} = 0 V		- 0.9	- 1.3	V
Reverse Recovery Time	t _{rr}	L = 9 A di/dt = 100 A/::2		50	80	ns
Reverse Recovery Time	Q _{rr}	- I _F = - 8 A, di/dt = 100 A/μs		80	120	nC

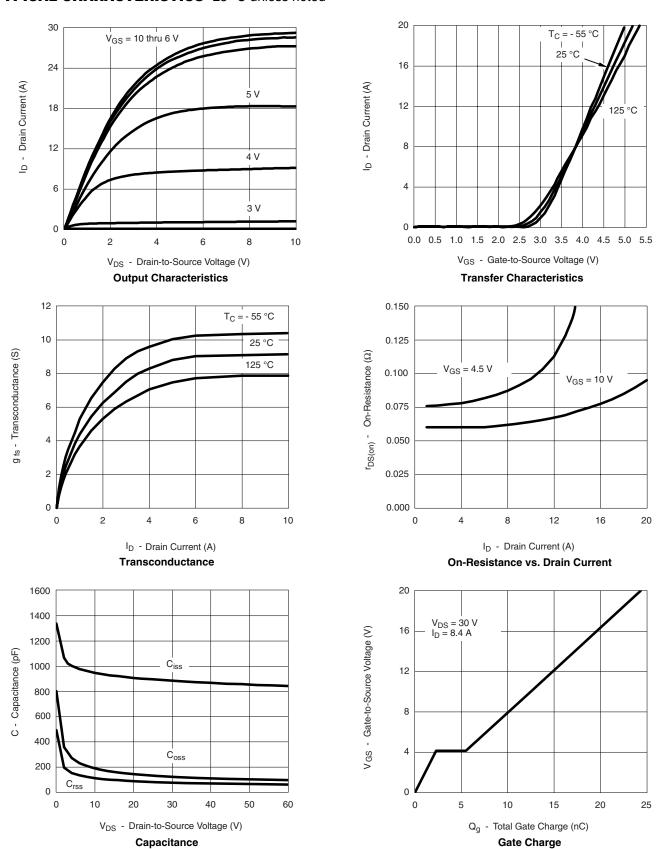
Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

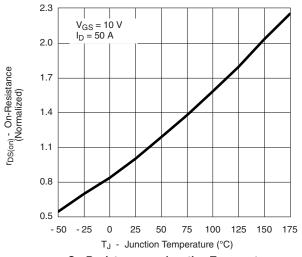


TYPICAL CHARACTERISTICS 25 °C unless noted

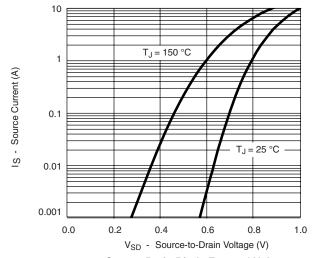




TYPICAL CHARACTERISTICS 25 °C unless noted

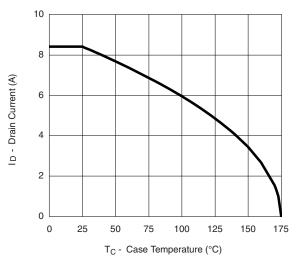




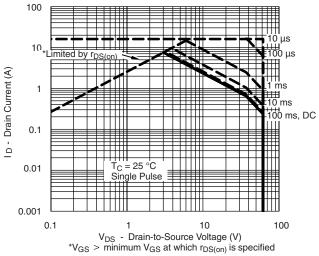


Source-Drain Diode Forward Voltage

THERMAL RATINGS



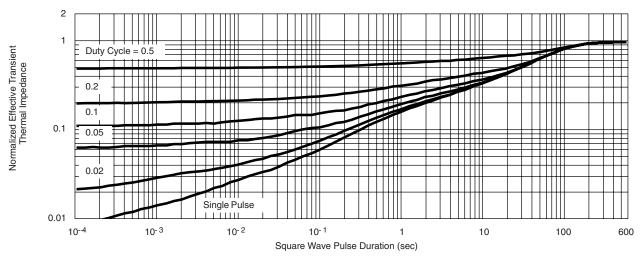
Drain Current vs. Case Temperature



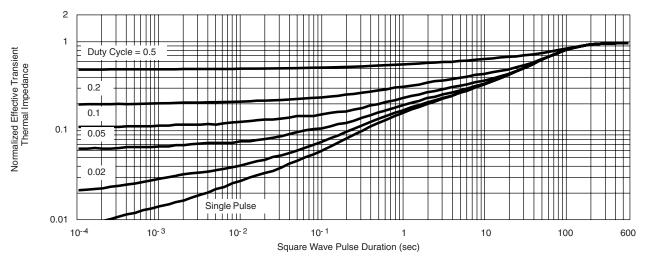
Safe Operating Area



THERMAL RATINGS



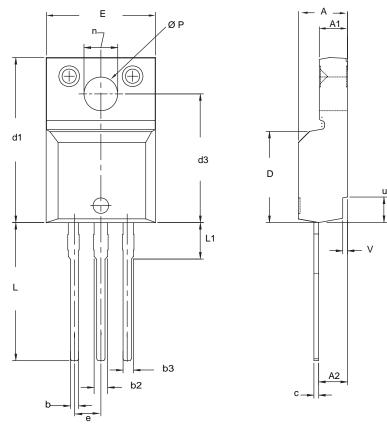
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



DIM.	MILLIN	METERS	INC	INCHES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	2.54 BSC		BSC	
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

DWG: 5972

Notes

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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